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Soggetti	Integrated circuits - Design and construction Multichip modules (Microelectronics) - Design and construction
Lingua di pubblicazione	Inglese
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Livello bibliografico	Monografia
Nota di bibliografia	Includes bibliographical references and indexes.
Nota di contenuto	SiP design and simulation platform -- Basic knowledge of package -- SiP production process -- New package technologies -- SiP design and simulation flow -- Central library -- Schematic input -- Multi-board project management and schematic concurrent design -- Layout creation and setting -- Constraint rules management -- Wire bond design -- Cavity and chip stack design -- FlipChip and RDL design -- Route and plane -- Embedded passives design -- RF circuit design -- Layout concurrent design -- 3D real-time DRC -- Design review -- Manufacture data output -- SiP simulation technology.